

Global and China Wire Bonder Equipment Market Research by Company, Type & Application 2013-2025

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Abstracts

SUMMARY

Wire bonder equipment is the machinery used for making interconnects between an IC or any other semiconductor device at the time of packaging. This interconnection ensures the flow of electricity in the semiconductor device. The thin-wire used to make these connections are usually made of copper, gold, aluminum, or silver. Wire bonder equipment is part of the semiconductor assembly and packaging process.

Market Segment as follows:

By Type

Ball bonders

Stud-bump bonders

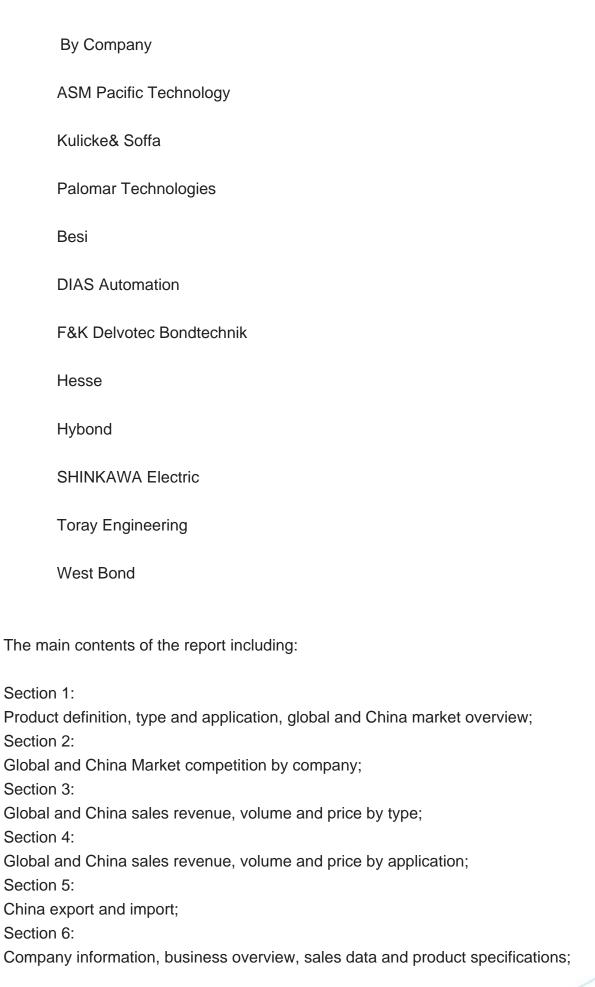
Wedge bonders

By Application

Integrated Device Manufacturers (IDMs)

Outsourced Semiconductor Assembly and Test (OSAT)







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